

**PATENT ASSIGNMENT**

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NATURE OF CONVEYANCE:	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
Yasuyoshi HYODO	01/16/2007
Kazuo KOHMURA	02/20/2007
Nobutoshi FUJII	02/16/2007
Nobutaka KUNIMI	02/26/2007
Keizo KINOSHITA	01/23/2007

**RECEIVING PARTY DATA**

Name:	ASM JAPAN K.K.
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City:	Tama-shi, Tokyo
State/Country:	JAPAN
Postal Code:	206-0025

Name:	ULVAC, Inc.
Street Address:	2500 Hagisono
City:	Chigasaki-shi, Kanagawa
State/Country:	JAPAN
Postal Code:	253-8543

Name:	NEC Corporation
Street Address:	7-1, Shiba 5-chome
City:	Minato-ku, Tokyo
State/Country:	JAPAN

**PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	11604598

**CORRESPONDENCE DATA**

**500236130**

**PATENT  
 REEL: 018983 FRAME: 0520**

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ASMJP3.206AUS

NAME OF SUBMITTER:

Katsuhiko Arai

Total Attachments: 1

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ASSIGNMENT

WHEREAS, We, Yasuyoshi HYODO, a Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo, 206-0025 Japan; Kazuo KOHMURA, a Japanese citizen, residing at 580-32, Nagaura, Sodegaura-shi, Chiba, Japan; Nobutoshi FUJII, a Japanese citizen, residing at 2500 Hagisono, Chigasaki-shi, Kanagawa 253-8543 Japan; Nobutaka KUNIMI, a Japanese citizen, residing at 1-98, Kasugadenaka 3-chome, Konohana-ku, Osaka-shi, Osaka 554-8558 Japan and Keizo KINOSHITA, a Japanese citizen, residing at 7-1, Shiba 5-chome, Minato-ku, Tokyo, Japan, have invented certain new and useful improvements in a METHOD FOR FORMING POROUS INSULATION FILM for which we have executed an application for Letters Patent in the United States, on November 27, 2006 as Application Serial No. 11/604,598;

AND WHEREAS, ASM JAPAN K. K., a Japan Corporation, with its principal place of business at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan; ULVAC, Inc., a Japan Corporation with its principal place of business at 2500 Hagisono, Chigasaki-shi, Kanagawa 253-8543 Japan, and NEC Corporation, with its principal place of business at 7-1, Shiba 5-chome, Minato-ku, Tokyo, Japan (hereinafter collectively "ASSIGNEES"), desire jointly to acquire the entire right, title, and interest in and to the said improvements and the said Application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the said inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEES, their successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEES, their successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEES, their successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEES, their successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

This 16 day of January, 2007

Yasuyoshi Hyodo  
Yasuyoshi HYODO

This 20 day of February, 2007

Kazuo Kohmura  
Kazuo KOHMURA

This 16 day of February, 2007

Nobutoshi Fujii  
Nobutoshi FUJII

This 26 day of February, 2007

Nobutaka Kunimi  
Nobutaka KUNIMI

This 23 day of January, 2007

Keizo Kinoshita  
Keizo KINOSHITA